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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION # 20472**

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**Issue Date:** 29-May-2014

**TITLE:** Final Notification for Transfer of LCX devices from TS60 wafer technology to TS18 Wafer Technology

**PROPOSED FIRST SHIP DATE:** 29-Aug-2014

**AFFECTED CHANGE CATEGORY(S):** ON Semiconductor Fab Site

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or <[rich.field@onsemi.com](mailto:rich.field@onsemi.com)>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available

Contact your local ON Semiconductor Sales Office or <[jose.aguilar@onsemi.com](mailto:jose.aguilar@onsemi.com)>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <[quality@onsemi.com](mailto:quality@onsemi.com)>.

**DESCRIPTION AND PURPOSE:**

This is a Final Process Change Notice informing ON Semiconductor customers that Logic Devices under the LCX family are now qualified to be manufactured in the TS18 wafer technology line of Tower Semiconductor Ltd in Migdal Haemek, Israel. This device family is currently being fabricated in the TS60 wafer technology line of the said wafer fabrication facility.

The Tower Semiconductor Ltd Migdal Haemek, Israel fab is certified according to ISO/TS16949 standard; and has been the wafer fab source of majority of the Logic Devices of On Semiconductors Inc.

Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed ON Semiconductor standards. ON Semiconductor recommends that customers evaluate sample units in each associated application circuit to ensure there are no unexpected electrical incompatibilities.



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**RELIABILITY DATA SUMMARY:**

**Reliability Test Results:**

Test	Conditions	Interval	Results
MSL1 @260C	24hr bake at 125C+168hr 85/85 +3 IR at 260C		0/240
Autoclave	Ta: 121C; RH: 100; Pressure: 15psig	96hr	0/240
HAST	Ta=130C; RH=85%; 18.8psig	168hr	0/240
HTSL	Ta: 150C	504hr	0/240
TC	Ta: -65C to 150C air to air	504cyc	0/160
PD			0/30
SD	Ta: 245C		0/45

**ELECTRICAL CHARACTERISTIC SUMMARY:**

The integrated circuits electrical specifications will remain identical.  
A full electrical characterization over the temperature range will be performed for each product to check the device functionality and electrical specifications.

**CHANGED PART IDENTIFICATION:**

There will be no changes to standard device markings. Normal assembly lots traceability codes will identify the wafer fab source.

**List of affected General Parts:**

MC74LCX240DTR2G	MC74LCX373DTG	MC74LCX573DTR2G
MC74LCX240DWR2G	MC74LCX373DTR2G	MC74LCX573DTR2GH
MC74LCX244DTG	MC74LCX373DWR2G	MC74LCX573DWG
MC74LCX244DTR2G	MC74LCX374DTR2G	MC74LCX573DWR2G
MC74LCX244DTR2GH	MC74LCX374DWR2G	MC74LCX574DTG
MC74LCX244DWG	MC74LCX540DTG	MC74LCX574DTR2G
MC74LCX244DWR2G	MC74LCX540DTR2G	MC74LCX574DTR2GH
MC74LCX244MNTWG	MC74LCX540DWR2G	MC74LCX574DWR2G
MC74LCX245DTG	MC74LCX541DTG	NLV74LCX244DTR2G
MC74LCX245DTR2G	MC74LCX541DTR2G	NLV74LCX245DTR2G
MC74LCX245DWG	MC74LCX541DWG	NLV74LCX373DTR2G
MC74LCX245DWR2G	MC74LCX541DWR2G	NLV74LCX573DTR2G
MC74LCX245MNTWG	MC74LCX573DTG	